

HOSTAFORM®

Chemical abbreviation according to ISO 1043-1: POM Molding compound ISO 29988- POM-K, M-GNR, 03-002, K5 POM copolymer Injection molding type, with special chalk modified; good wear properties; good chemical resistance to solvents, fuel and strong alkalis as well as good hydrolysis resistance; high resistance to thermal and oxidative degradation. UL-registration in natural and a thickness more than 1.57 mm as UL 94 HB, temperature index UL 746 B electrical 105 °C, mechanical 90 °C (tensile impact) and 80 °C (tensile). Burning rate ISO 3795 and FMVSS 302 < 100 mm/min for a thickness more than 1 mm. Ranges of applications: for unlubricated or once-only-lubricant sliding Parts. FMVSS = Federal Motor Vehicle Safety Standard (USA) UL = Underwriters Laboratories (USA)

Product information

Resin Identification Part Marking Code	POM >POM<		ISO 1043 ISO 11469
Rheological properties			
Melt volume-flow rate Temperature Load	7.5 190 2.16	-	ISO 1133
Moulding shrinkage, parallel Moulding shrinkage, normal [1]: @ 195°C	2.1 ^[1] 1.8 ^[1]		ISO 294-4, 2577 ISO 294-4, 2577
Typical mechanical properties			
Tensile modulus Tensile stress at yield, 50mm/min Tensile strain at yield, 50mm/min Nominal strain at break Flexural modulus Tensile creep modulus, 1h Tensile creep modulus, 1000h Charpy impact strength, 23°C Charpy impact strength, -30°C Charpy notched impact strength, 23°C Charpy notched impact strength, -30°C Ball indentation hardness, H 358/30 Poisson's ratio [C]: Calculated	8 22 2900 2500 1400 100 100 5 5	MPa % MPa	ISO 527-1/-2 ISO 527-1/-2 ISO 527-1/-2 ISO 527-1/-2 ISO 178 ISO 899-1 ISO 899-1 ISO 179/1eU ISO 179/1eU ISO 179/1eA ISO 179/1eA
Thermal properties			
Melting temperature, 10°C/min Temperature of deflection under load, 1.8 MPa Coefficient of linear thermal expansion (CLTE), parallel		°C E-6/K	ISO 11357-1/-3 ISO 75-1/-2 ISO 11359-1/-2
Thermal conductivity of melt Specific heat capacity of melt		W/(m K) J/(kg K)	ISO 22007-2 ISO 22007-4



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Flammability			
Burning Behav. at 1.5mm nom. thickn.	HB	class	IEC 60695-11-10
Thickness tested		mm	IEC 60695-11-10
Burning Behav. at thickness h		class	IEC 60695-11-10
Thickness tested	3.18	mm	IEC 60695-11-10
UL recognition	yes		UL 94
Electrical properties			
Relative permittivity, 100Hz	4.2		IEC 62631-2-1
Relative permittivity, 1MHz	4.2		IEC 62631-2-1
Dissipation factor, 100Hz		E-4	IEC 62631-2-1
Dissipation factor, 1MHz		E-4	IEC 62631-2-1
Volume resistivity		Ohm.m	IEC 62631-3-1
Surface resistivity Electric strength	1E14	kV/mm	IEC 62631-3-2 IEC 60243-1
Comparative tracking index	600		IEC 60112
Comparative tracking mook	000		
Physical/Other properties			
Humidity absorption, 2mm	0.2		Sim. to ISO 62
Water absorption, 2mm	0.65		Sim. to ISO 62
Density	1440	kg/m ³	ISO 1183
Injection			
Drying Recommended	no		
Drying Temperature	100	°C	
Drying Time, Dehumidified Dryer	3 - 4		
Processing Moisture Content	≤0.2		
Melt Temperature Optimum	200		
Min. melt temperature	190		
Max. melt temperature Screw tangential speed	210		
	<0.3	m/c	
•	≤0.3 100		
Mold Temperature Optimum	100	°C	
Mold Temperature Optimum Min. mould temperature	100	°C °C	
Mold Temperature Optimum	100 80	2° 2° 2°	
Mold Temperature Optimum Min. mould temperature Max. mould temperature	100 80 120 60 - 120	2° 2° 2°	
Mold Temperature Optimum Min. mould temperature Max. mould temperature Hold pressure range	100 80 120 60 - 120	°C °C °C MPa MPa	
Mold Temperature Optimum Min. mould temperature Max. mould temperature Hold pressure range Back pressure	100 80 120 60 - 120 2	°C °C °C MPa MPa	
Mold Temperature Optimum Min. mould temperature Max. mould temperature Hold pressure range Back pressure Ejection temperature	100 80 120 60 - 120 2	°C °C MPa MPa °C	
Mold Temperature Optimum Min. mould temperature Max. mould temperature Hold pressure range Back pressure Ejection temperature Characteristics	100 80 120 60 - 120 2 140	°C °C MPa MPa °C	

Low wear / Low friction

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Special characteristics





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Additional information

Injection molding

Preprocessing

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

Processing

Standard injection moulding machines with three phase (15 to 25 D) plasticating screws will fit.

Postprocessing

Conditioning e.g. moisturizing is not necessary.

Processing Notes

Pre-Drying

Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying may be necessary to prevent splay and odor problems.

Storage

The product can then be stored in standard conditions until processed.

Automotive

OEM BMW Bosch Continental STANDARD GS93016 N28 BN22-X016 TST N 055 54.09

ADDITIONAL INFORMATION

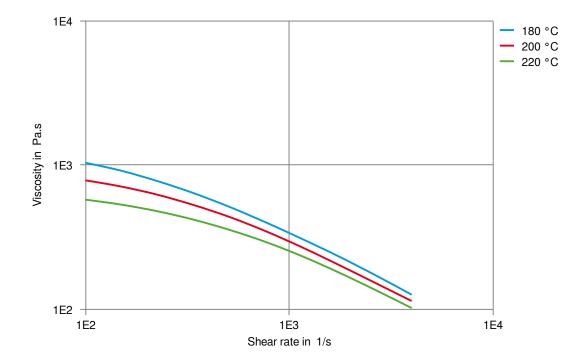
Natural





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Viscosity-shear rate

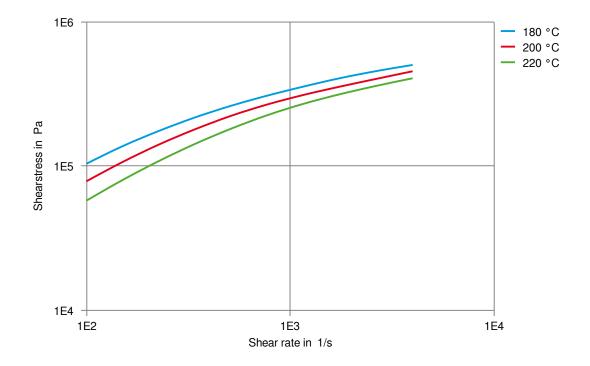






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Shearstress-shear rate

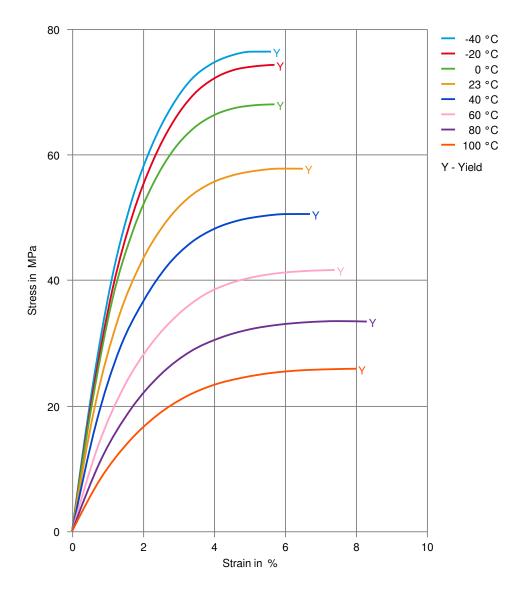






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Stress-strain

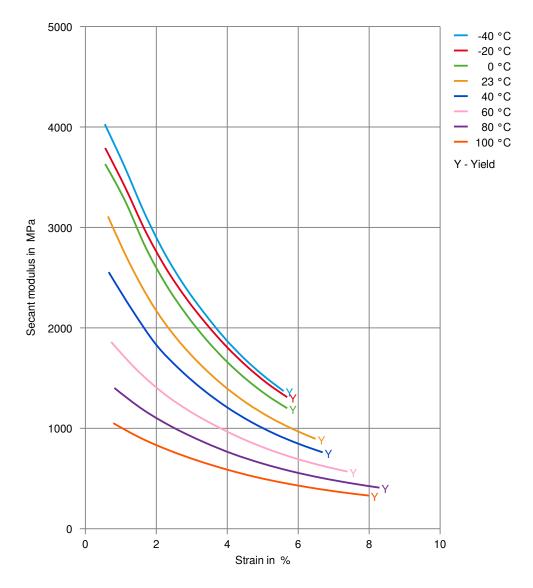






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Secant modulus-strain

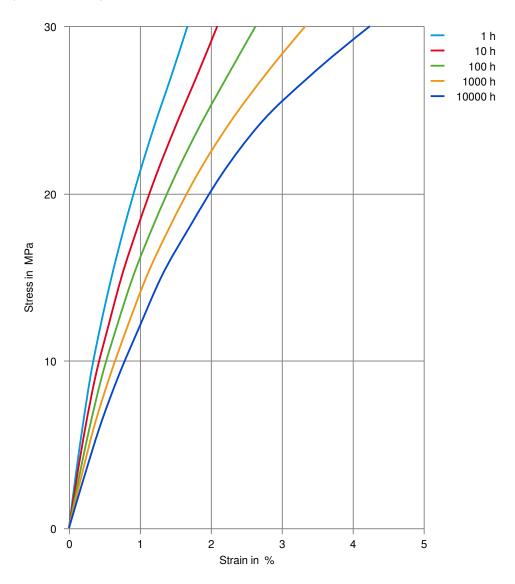






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Stress-strain (isochronous) 23°C

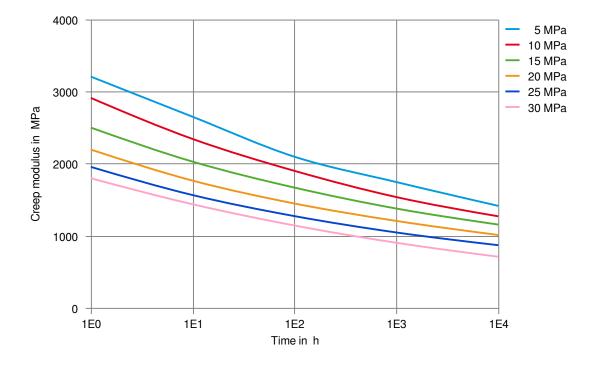






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Creep modulus-time 23°C



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